

SOT1358-1

plastic extremely thin small outline package; no leads; 7 terminals; body 1.1 x 2.1 x 0.5 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	XSON7
Package type industry code	XSON7
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	12-9-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.05	-	2.1	2.2	mm
E	package width	1	-	1.1	1.2	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	7	-	



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2. Package outline

XSON7: plastic extremely thin small outline package; no leads; 7 terminals; body 1.1 x 2.1 x 0.5 mm SOT1358-1

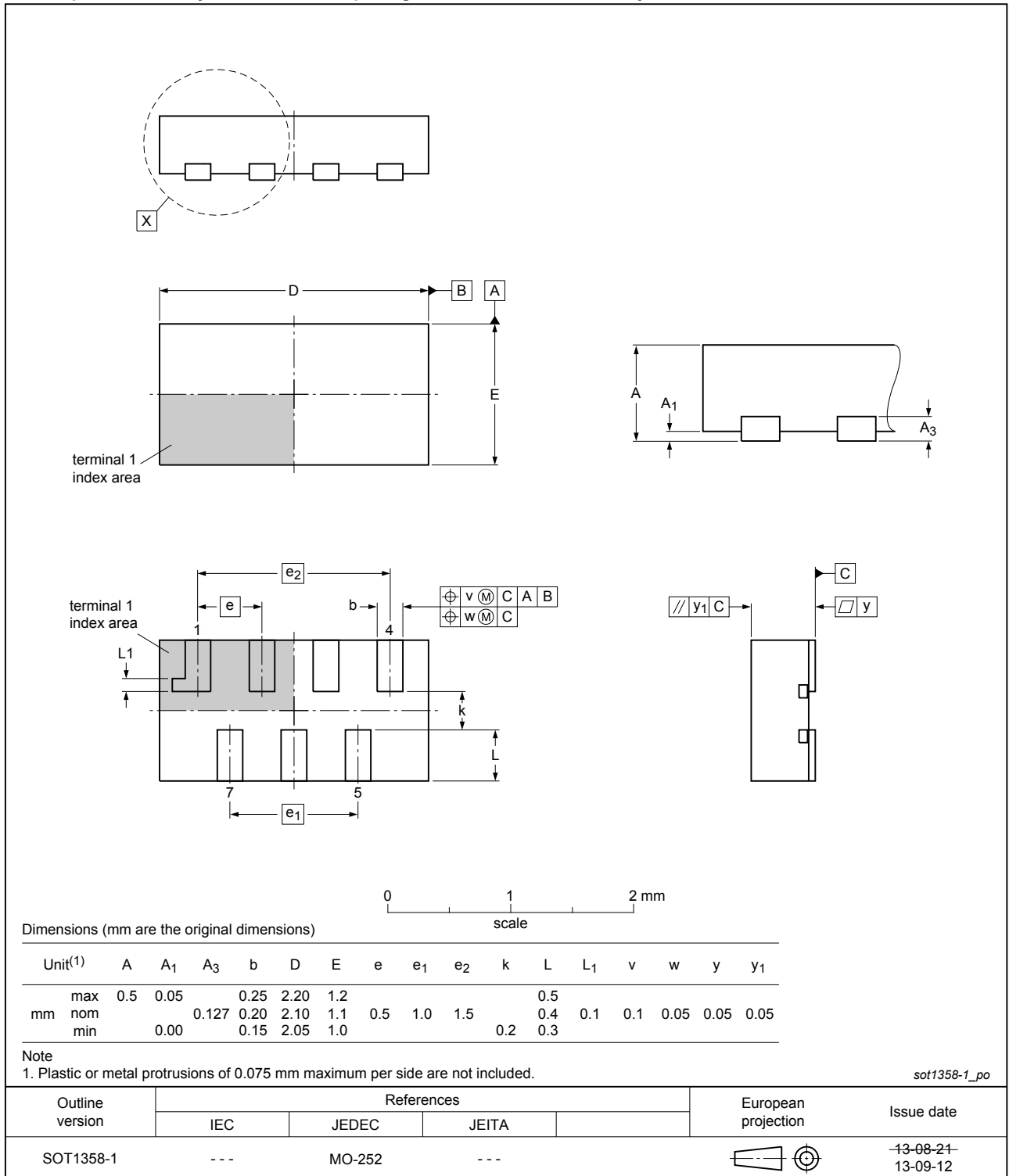


Fig. 1. Package outline XSON7 (SOT1358-1)

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4. Legal information

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